

Study on Thermal Stability of Probe Mark



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Background

- While hot temperature testing, we can see obvious probe mark shift.
- Sometimes probe marks touch edge of pad if proper alignment didn't performed.
- How can we safely hit the pad by probe tip?





- We want to have a well centered probe mark on the pad upon high temperature testing environment.
- After alignment, probe mark shift has to be always back to "Zero".

Minimizing probing shift against temperature

- At 150'C, since start probing, probe mark start to shift.
- Whatever it is, after alignment, the probe mark shift is "Zero".
- After alignment, continue to probe remain dies, then shift start to appear again.
- After alignment, the shift back to "Zero" again.



Property of us

Shift 1

- Specially designed system calibration mark system.
- All symmetric design
- Heat blocking & spreading
- Right air circulation
- Making the needed spot rigid





Result

• Hitting the very same spot after alignment



Findings: Be smart?

• Seeking smart way to perform alignment interval or coordinate.



- Device(Wafer and probe card) is different always.
- Increasing number of alignment will increase accuracy and control. But it will decrease throughput and overall system efficiency.



- All symmetric design concept, heat blocking, making needed spot rigid, but it will be NEVER perfect.
- By our own reference mark optical calibration system, as long as alignment performed, all the shift will be "Zero".
- Then, how often should we perform it?

Without knowing, perform alignment every 20minutes, Shift will be controlled within 9um maximum.





• We want to control shift efficient way.



Key data 3

We control shift by time bases alignment. \bullet



Conclusion

- Our system's key value (Optic system) is once we perform alignment, any probe mark at any condition will get back to it's original position.
- To avoid often alignment time consuming, smart way of doing alignment by time + tolerance base is available.

Follow-On Work

- "Zero" system aging time for device change over especially temperature testing product.
 - Start probing immediately once prober reached target temperature.
 - To get rid of aging time.
 - To get fastest device change over time.

